

ChipLED 0603 Series 1.6\*0.8\*0.6mm Single Color Package



#### **ChipLED 0603 Yellow Series**

## **Description**

- These ChipLEDs are designed in an industry-standard package.
- Various LED colors are available in seven compact, single-color packages.
- $\bullet$  The YY0603 has the industry-standard 1.6 mm  $\times$  0.8 mm footprint, which is excellent for all-around use.
- These ChipLEDs are packaged in tape and reel with 4000 units in general per reel.
- All packages are compatible with IR reflow solder processes.
- The small size and wide viewing angle,

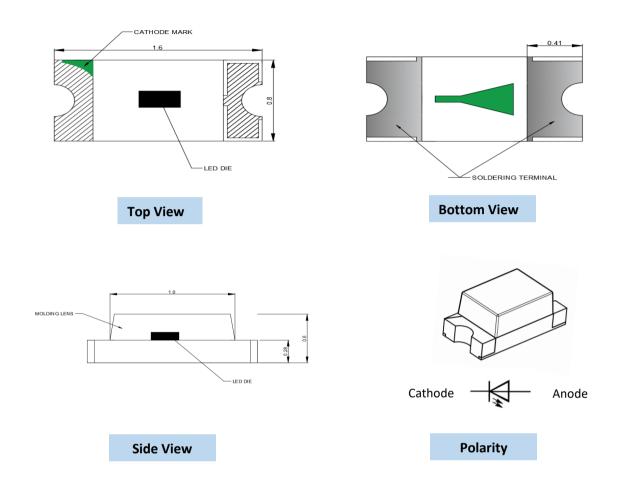
#### **Features and Benefits**

- Small size, Industry-standard footprint
- Compatible with Infrared solder process
- Compatible with automatic placement equipment
- Operating temperature range of -40°C to +85°C
- Viewing angle: 140°
- Right angle and reverse mount package available
- Various colors available
- Available in 8-mm tape, 7" reel (4000 pcs/reel), Meets EIA STD package
- Moisture sensitivity level: 3
- Halogen-free , RoHS and REACH compliant

## **Applications**

- Keypad backlighting
- Push-button and switch backlighting
- LCD backlighting
- Symbol backlighting
- Front-panel indicator
- Optical indicator
- Home and smart appliances
- Wearable and portable devices
- Toys
- Displays for industrial control systems

# **Package Drawing**



#### Note:

- 1. All dimensions are in millimeters.
- 2. Tolerance is ±0.1 mm unless otherwise specified.

Part Table									
#	Part Number	Emission Color	Polarity	Znener	Binning Current (mA)	Luminous Intensity (mcd)	Dominant Wavelength (nm)	Forward Voltage (V)	Remark
1	YY0603YE-NN1S0-T2AR4	Yellow			5	20-34	586-594	1.8-2.3	
2	YY0603YE-NN3S0-T2AR4	Yellow			20	85-175	586-594	1.8-2.4	
3	YY0603YE-NZ3S0-T2AR4	Yellow		available	20	100-210	588-596	1.8-2.4	
4	YY0603YE-RN1S0-T2AR4	Yellow	Reverse		5	85-210	586-594	1.8-2.4	
5	YY0603YE-RN3S0-T2AR4	Yellow	Reverse		20	300-620	588-594	1.8-2.4	
6	YY0603YE-RN3S2-T2AR4	Yellow	Reverse		20	430-900	588-594	1.8-2.4	High Brightness

## Absolute Maximum Ratings for at Ta = 25°C

Parameter	Symbol	Rating	Unit	
Reverse Voltage	$V_R$	5	V	
Forward Current	I <sub>F</sub>	20	mA	
Peak Forward Current(Duty 1/10 @1KHz)	I <sub>FP</sub>	60	mA	
Power Dissipation	Pd	48	mW	
Electrostatic Discharge	ESD <sub>HBM</sub>	2000	V	
Operating Temperature	Topr	-40 ~ +85	$^{\circ}$ C	
Storage Temperature	Tstg	-40 ~ +85	$^{\circ}$ C	
Soldering Temperature	Tsol	Reflow Soldering : 260 °C for 10 sec.		
Solueting reinperature		Hand Soldering : 300 °C for 3 sec.		

#### Luminous Intensity (Iv) Bin Limits

Bin ID	Luminous Intensity(mcd)			
	Min.	Max.		
P11	20	24		
P12	24	28		
P13	28	34		
P19	85	100		
P20	100	120		
P21	120	145		
P22	145	175		
P23	175	210		
P26	300	360		
P27	360	430		
P28	430	520		
P29	520	620		
P30	620	750		
P31	750	900		

#### Forward Voltalge(V) Bin Limits

Bin ID	Forward Voltage(V)			
	Min.	Max.		
VE	1.8	1.9		
VF	1.9	2.0		
VG	2.0	2.1		
VH	2.1	2.2		
VI	2.2	2.3		
VJ	2.3	2.4		

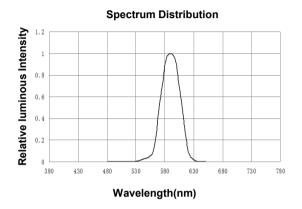
#### Dominant Wavelength (nm) Bin Limits

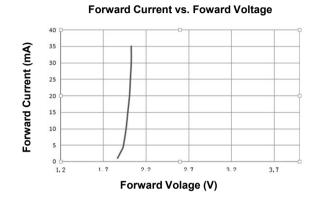
Bin ID	Dominant Wavelength (nm)			
ыны	Min.	Max.		
Y4	586	588		
Y5	588	590		
Y6	590	592		
Y7	592	594		

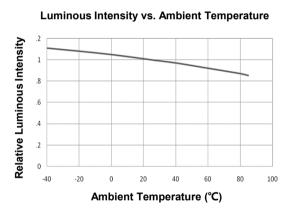
- \* Tolerance of measurement of luminous intensity is ±10%.
- \* Tolerance of measurement of forward voltage is ±0.05V.
- \* Tolerance of measurement of dominant wavelength is  $\pm 1 \ \text{nm}.$

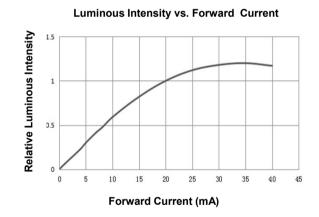
## TYPICAL ELECTRO-OPTICAL CHARATERISTICS CURES(Ta=25°C)

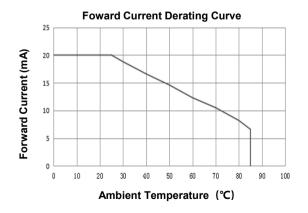
The data below are collected from statistical figures that do not necessarily correspond to the actual parameters of each single LED. Hence, these data will be changed without further notice.

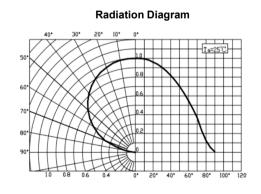






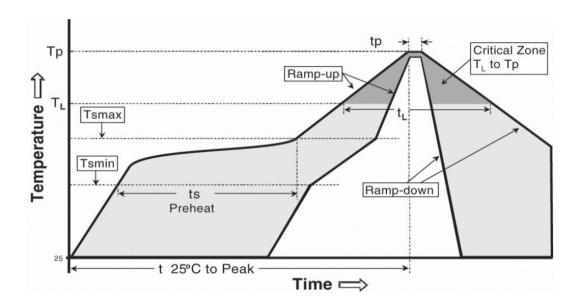






#### **REFLOW SOLDERING**

- The ChipLED is rated as a MSL3 as general request product.
- The recommended floor life out of bag is 24hrs.
- The temperature profile is as below.



#### IPC/JEDEC J-STD-020C

Profile Feature	Pb-Free Assembly
Average ramp-up rate(Tsmax to Tp)	3°C/second max.
Preheat	
- Temperature Min(Ts <sub>min</sub> )	<b>150℃</b>
- Temperature Max(Ts <sub>max</sub> )	200℃
- Time(Tsmin to Ts <sub>max</sub> )	60-180 seconds
Time mainted above	
- Temperature(T <sub>L</sub> )	217℃
- Time(T <sub>L</sub> )	60-150 seconds
Peak Temperature(Tp)	<b>260</b> ℃
Time within 5°C of actual peak Temperature(tp) <sup>2</sup>	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to peak Temperature	8 minutes max.

#### **Moisture Sensitivity**

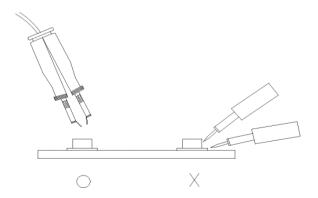
- Yongyu recommends keeping ChipLEDs in the provided, resealable moisture-barrier packaging (MBP) until immediately prior to soldering. Unopened MBPs that contain ChipLEDs do not need special storage for moisture sensitivity.
- Once the MBP is opened, ChipLEDs may be stored as MSL 3 per IPC/JEDEC J-STD-020C, meaning they have one year of floor life in conditions of  $\leq 30$  °C/60% relative humidity (RH). Regardless of the storage condition, Yongyu LED recommends sealing any unsoldered ChipLEDs in the original

#### Handling

- The packaging sizes of these SMD products are very small. Users are required to handle with care.
- To avoid damaging the product's surface and interior device, it is recommended to choose a special nozzle to pick up the SMD products during the process of SMT production. If handling is necessary, take special care when picking up these products.

#### Repairing

Repair should not be recommended after SMT production. When repairing is needed, a double-head soldering iron should be used (as below figure). It should be assured before handing whether the electrical and optical characteristics of the LEDs will or will not be damaged by repairing.



### **PACKING**

- The LEDs are packed in cardboard boxes after packaging in normal or anti-electrostatic bags.
- Cardboard boxes will be used to protect the LEDs from mechanical shock during transportation.
- The boxes are not water resistant, and they must be kept away from water and moisture.
- The reel pack is applied in SMD LED.
- 4000pcs per reel.

